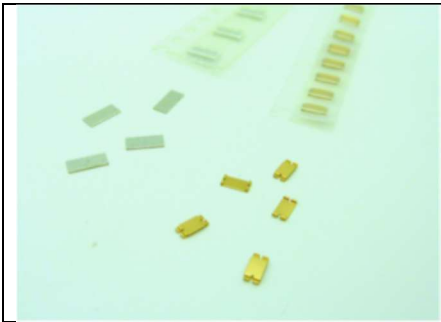


# SMD GROUNDING PLATE

Kitagawa series: OGP

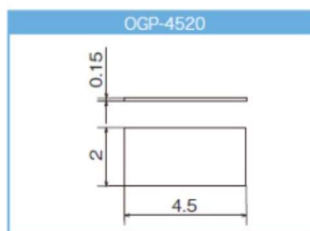
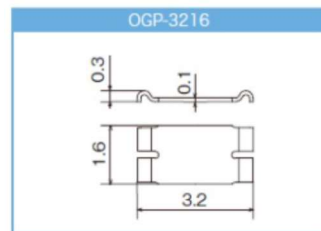


- Solves contact failures caused by solder flux.
- Reliable contact provided due to fibreglass reinforcement.

## MATERIAL

Part Number	Material	Height
OGP-3216	Brass (Au plating)	0.3mm
OGP-4520	Brass (Sn reflow plating)	0.15mm

## DIMENSIONS

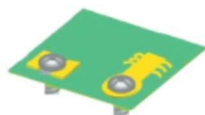


Unit : mm

## APPLICATION EXAMPLES



- Effective contact
  - OGP protects PC board from damage such as circuit pattern damage by vibration etc at FG area.
  - Gold plating is available at the required location on PC board.



- Alternative components to washers and lug terminals
  - More compact than conventional lug terminals.
  - OGP prevents loosening of screws when subject to vibration.